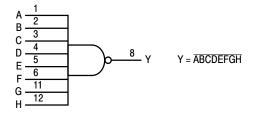
# 8-Input NAND Gate

# **High-Performance Silicon-Gate CMOS**

The MC74HC30 is identical in pinout to the LS30. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- These are Pb-Free Devices



PINS 9, 10, 13 = NO CONNECTION  $\begin{array}{c} \text{PIN 14 = V}_{CC} \\ \text{PIN 7 = GND} \end{array}$ 

Figure 1. Logic Diagram



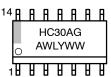
# ON Semiconductor®

http://onsemi.com

#### MARKING DIAGRAMS



SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G

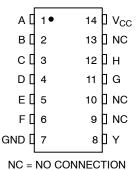


A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN ASSIGNMENT**



#### **FUNCTION TABLE**

Inputs A through H	Output Y
All inputs H	L
One or more inputs L	H

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	٧
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	-1.5 to V <sub>CC</sub> + 1.5	٧
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>in</sub>	DC Input Current, per Pin	±20	mA
I <sub>out</sub>	DC Output Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air SOIC Package TSSOP Package		mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)			6.0	٧
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)			V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	(Figure 2)	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V	0 0 0	1000 500 400	ns

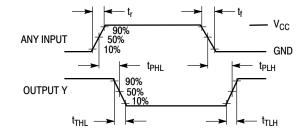
# DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

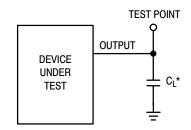
			Gua	Guaranteed Limit		mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$V_{out}$ = 0.1 V or $V_{CC}$ – 0.1 V $ I_{out}  \le 20 \mu A$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{out}$ = 0.1 V or $V_{CC}$ - 0.1 V $ I_{out}  \le 20 \mu A$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20  \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH} \text{ or } V_{IL} \qquad \begin{vmatrix} I_{out} \end{vmatrix} \le 4.0 \text{ mA} \\  I_{out}  \le 5.2 \text{ mA} \end{vmatrix}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20  \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} = V_{IH} \text{ or } V_{IL} \qquad \begin{vmatrix} I_{out} \end{vmatrix} \le 4.0 \text{ mA} \\  I_{out}  \le 5.2 \text{ mA} \end{vmatrix}$	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
I <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	2	20	40	μΑ

# AC ELECTRICAL CHARACTERISTICS ( $C_L$ = 50 pF, Input $t_r$ = $t_f$ = 6 ns)

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub> V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Any Input to Output Y (Figures 2 and 3)	2.0 4.5 6.0	175 35 30	220 44 37	265 53 45	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 2 and 3)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	-	10	10	10	pF

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
$C_{PD}$	Power Dissipation Capacitance (Per Gate)	27	pF





<sup>\*</sup>Includes all probe and jig capacitance

Figure 2. Switching Waveforms

Figure 3. Test Circuit

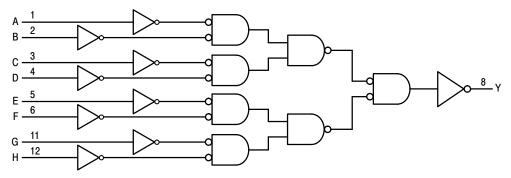


Figure 4. Expanded Logic Diagram

# **ORDERING INFORMATION**

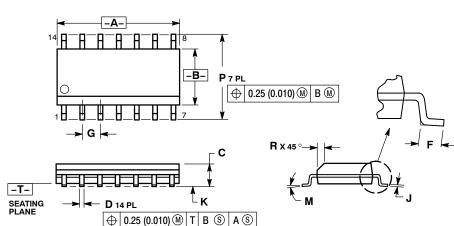
Device	Package	Shipping <sup>†</sup>
MC74HC30ADG	SOIC-14 (Pb-Free)	55 Units/Rail
MC74HC30ADR2G	SOIC-14 (Pb-Free)	2500/Tape & Reel
MC74HC30ADTR2G	TSSOP-14*	1

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>This package is inherently Pb-Free.

#### **PACKAGE DIMENSIONS**

#### SOIC-14 CASE 751A-03 **ISSUE J**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

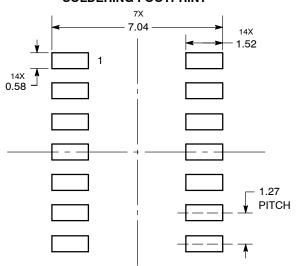
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0°	7 °
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

# **SOLDERING FOOTPRINT\***

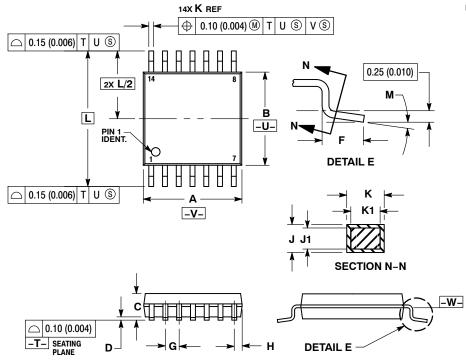


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### TSSOP-14 CASE 948G-01 **ISSUE B**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER

  - OTES:

    1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

    2. CONTROLLING DIMENSION: MILLIMETER.

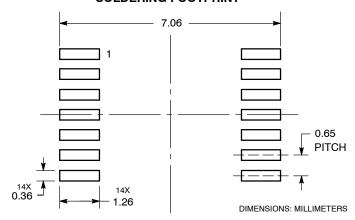
    3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

    4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

    5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION SHALL NOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
    6. TERMINAL NUMBERS ARE SHOWN FOR
  - REFERENCE ONLY.
    7. DIMENSION A AND B ARE TO BE

E	ETE		AT DA	TUM PL INC	ANE -W HES
	DIM	MIN	MAX	MIN	MAX
	Α	4.90	5.10	0.193	0.200
	В	4.30	4.50	0.169	0.177
	С		1.20		0.047
	D	0.05	0.15	0.002	0.006
	F	0.50	0.75	0.020	0.030
	G	0.65 BSC		0.026 BSC	
	Н	0.50	0.60	0.020	0.024
	J	0.09	0.20	0.004	0.008
	J1	0.09	0.16	0.004	0.006
	Κ	0.19	0.30	0.007	0.012
	K1	0.19	0.25	0.007	0.010
	L	6.40 BSC		0.252 BSC	
	M	0 °	8 °	0°	8 °

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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